

Temperature Dependence

The temperature-dependent variables in the models developed so far include the: Fermi potential, PHI, EG, bulk junction potential of the source-bulk and drain-bulk junctions, PB, the reverse currents of the pn junctions, I_S , and the dependence of mobility upon temperature. The temperature dependence of most of these variables is found in the equations given previously or from well-known expressions. The dependence of mobility upon temperature is given as

$$\mu_0(T) = \mu_0(T_0) \left(\frac{T}{T_0} \right)^{\text{BEX}}$$

where BEX is the temperature exponent for mobility and is typically -1.5.

$$v_{therm}(T) = \frac{KT}{q}$$

$$EG(T) = 1.16 - 7.02 \cdot 10^{-4} \cdot \left[\frac{T^2}{T + 1108.0} \right]$$

$$\text{PHI}(T) = \text{PHI}(T_0) \cdot \left(\frac{T}{T_0} \right) - v_{therm}(T) \left[3 \cdot \ln\left(\frac{T}{T_0}\right) + \frac{EG(T_0)}{v_{therm}(T_0)} - \frac{EG(T)}{v_{therm}(T)} \right]$$

$$v_{bi}(T) = v_{bi}(T_0) + \frac{\text{PHI}(T) - \text{PHI}(T_0)}{2} + \frac{EG(T_0) - EG(T)}{2}$$

$$V_{T0}(T) = v_{bi}(T) + \text{GAMMA} \left[\sqrt{\text{PHI}(T)} \right]$$

$$\text{PHI}(T) = 2 \cdot v_{therm} \ln\left(\frac{N_{SUB}}{n_i(T)}\right)$$

$$n_i(T) = 1.45 \cdot 10^{16} \cdot \left(\frac{T}{T_0} \right)^{3/2} \cdot \exp\left[EG \cdot \left(\frac{T}{T_0} - 1 \right) \cdot \left(\frac{1}{2 \cdot v_{therm}(T_0)} \right) \right]$$

For drain and source junction diodes, the following relationships apply.

$$\text{PB}(T) = \text{PB} \cdot \left(\frac{T}{T_0} \right) - v_{therm}(T) \left[3 \cdot \ln\left(\frac{T}{T_0}\right) + \frac{EG(T_0)}{v_{therm}(T_0)} - \frac{EG(T)}{v_{therm}(T)} \right]$$

$$I_S(T) = \frac{I_S(T_0)}{N} \cdot \exp\left[\frac{EG(T_0)}{v_{therm}(T_0)} - \frac{EG(T)}{v_{therm}(T)} + 3 \cdot \ln\left(\frac{T}{T_0}\right) \right]$$

where N is diode emission coefficient. The nominal temperature, T_0 , is 300 K.